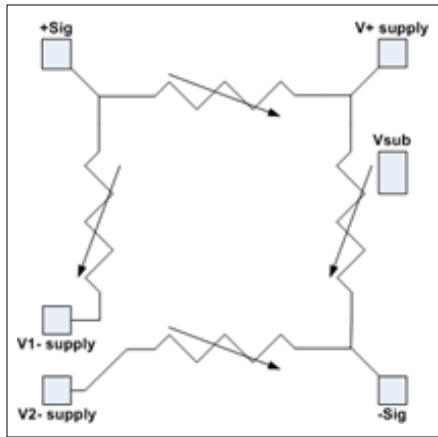
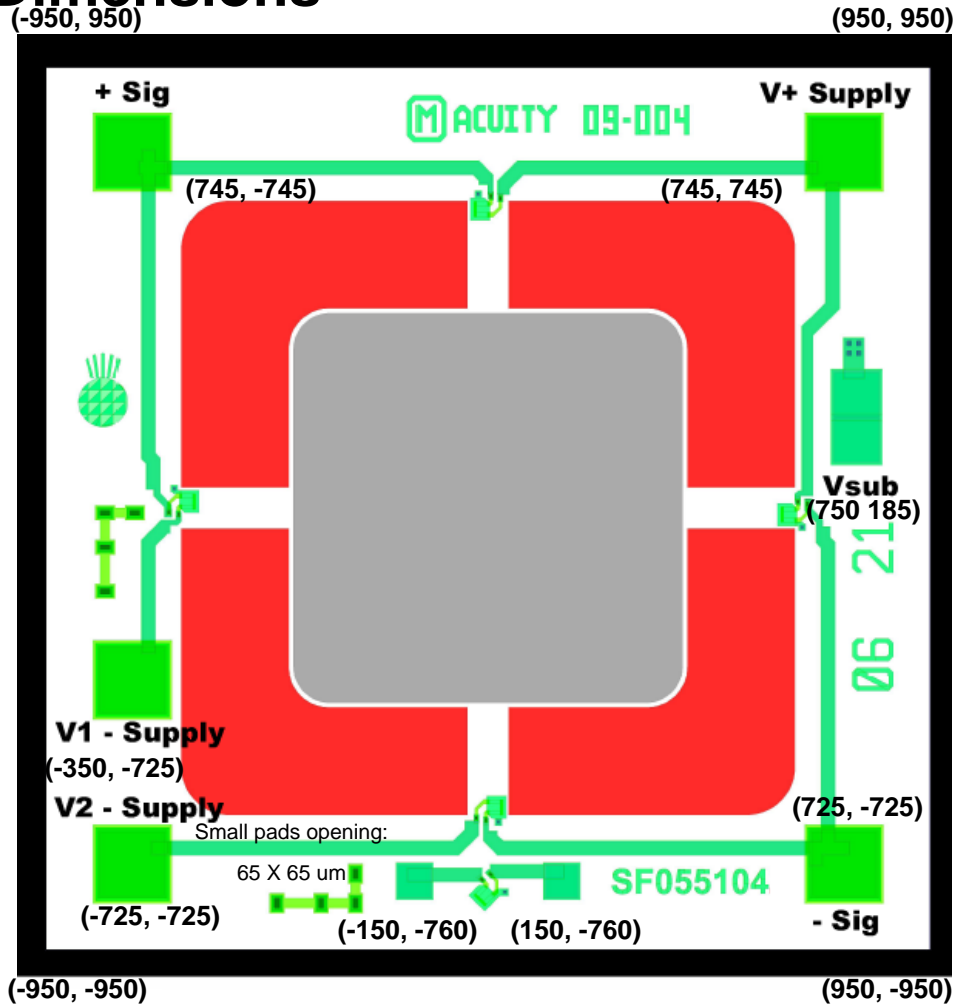


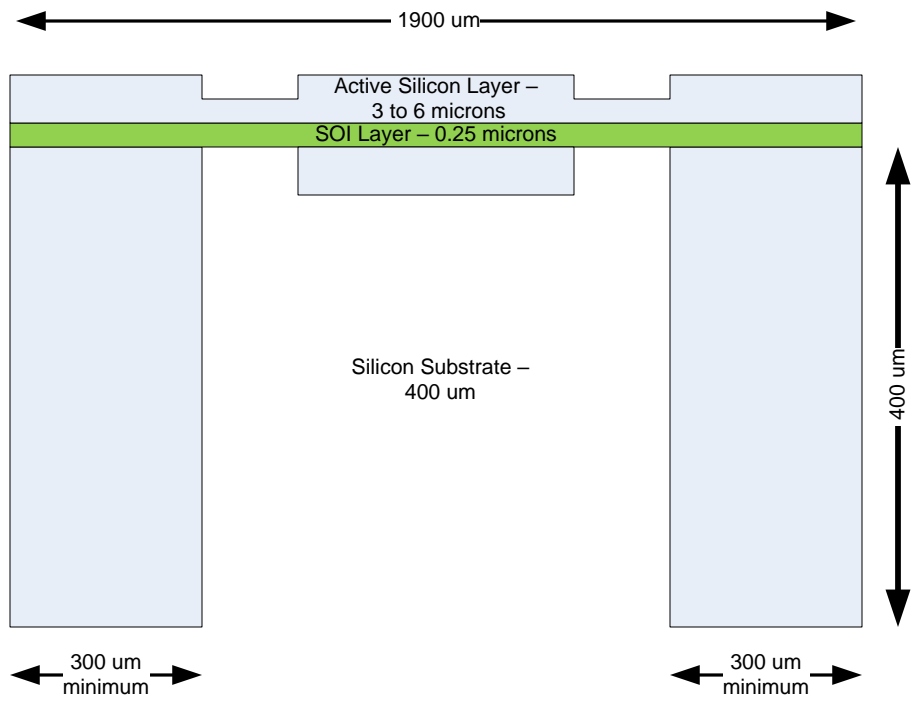
Dimensions



Equivalent Circuit and Pad-outs

NOTE:

1. All dimensions are in μm .
2. The coordinates for the center of each pad, shown as (XXX,YYY), are with respect to the center of the die.
3. Pad size openings are $130 \times 130 \mu\text{m}$ except the substrate pad which is $90 \times 180 \mu\text{m}$.
3. + Signal increases and - Signal decreases when pressure is applied from the top of the die.
4. AC3050 and AC3055 have identical bond-pad locations.
5. Acuity recommends wirebonding the VSUB connection to the most positive voltage on the bridge if driven from a DC supply.



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Acuity Incorporated	
AC3050 Series Dimensions and Pin-outs	
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